

AMENDMENT TRANSMITTAL LETTER (Small Entity)

Applicant(s): Donald Malcolm MacIntyre

Docket No.

MAI1003

Serial No.

09/045,507

Filing Date

3/20/98

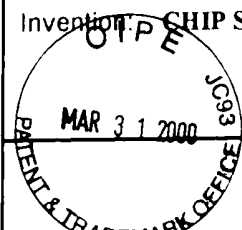
Examiner

D. Wille

Group Art Unit

2814

Invention: CHIP SCALE PACKAGE



TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

- ☒ Small Entity status of this application has been established under 37 CFR 1.27 by a verified statement previously submitted.
- ☐ A verified statement to establish Small Entity status under 37 FR 1.27 is enclosed.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$9.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0 x	\$39.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0230
A duplicate copy of this sheet is enclosed.
 - ☐ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☐ Any patent application processing fees under 37 CFR 1.17.

H. Donald Nelson
Signature

Dated: 3/20/2000

H. Donald Nelson, Reg. No. 28,980

I certify that this document and fee is being deposited on 3/20/2000 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

CC:

H. Donald Nelson

Typed or Printed Name of Person Mailing Correspondence



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MacIntyre

Assignee: Not assigned

Title: CHIP SCALE PACKAGES

Serial No.: 09/045,507

Filed: 3/20/98

Examiner: D. Wille

Group Art Unit: 2814

Attorney Docket No.: MAI1003

San Jose, California
March 19, 2000

COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Examiner's Office Action of 9/20/99, please amend the above-cited application as follows.

REMARKS

Claims 4, 6, 7, 15 and 17 are pending in the application and stand rejected. Applicant believes the Claims are patentable as they stand and request reconsideration and an early allowance.

The Examiner rejected Claims 4, 6, 7, 15 and 17 under 35 U.S.C. §103(a) as being unpatentable over Lin in view of Tsukamoto and Igarashi et al. The Examiner stated:

Lin shows a flip chip device (see Figure 5 and column 5, line 15) with a semiconductor chip 12 attached to an interposer board 22. Lin shows the interposer board attached to a PC board with layer of adhesive 36 but does not show a similar attachment 12 and 22, noting that while it is standard practice (column 2, line 22) it prevents rework. Note that if rework is not an issue, bonding is recommended. Lin also teaches that the thermal coefficient of expansion of the interposer should match that of the die (column 6, line 28). Lin shows vias 24 in the plate 22 with evaporated traces 26 (column 6, line 28). Lin shows vias 24 in the plate 22 with evaporated traces 26 (column 6, line 64) on the plate which connects contacts 16 to vias 24 and solder beads 32 are formed on the surface of 22. Lin shows that the metallization 26 can be evaporated and if performed after forming the hole it